

**/ Descriptions**

SOT-23          NPN                          Silicon NPN transistor in a SOT-23 Plastic Package.

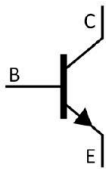
**/ Features**

High power gain, low noise figure, very low intermodulation distortion.

**/ Applications**

RF wideband amplifiers and oscillators.

**/ Equivalent Circuit**



**/ Pinning**



PIN1   Base          PIN 2   Emitter          PIN 3   Collector

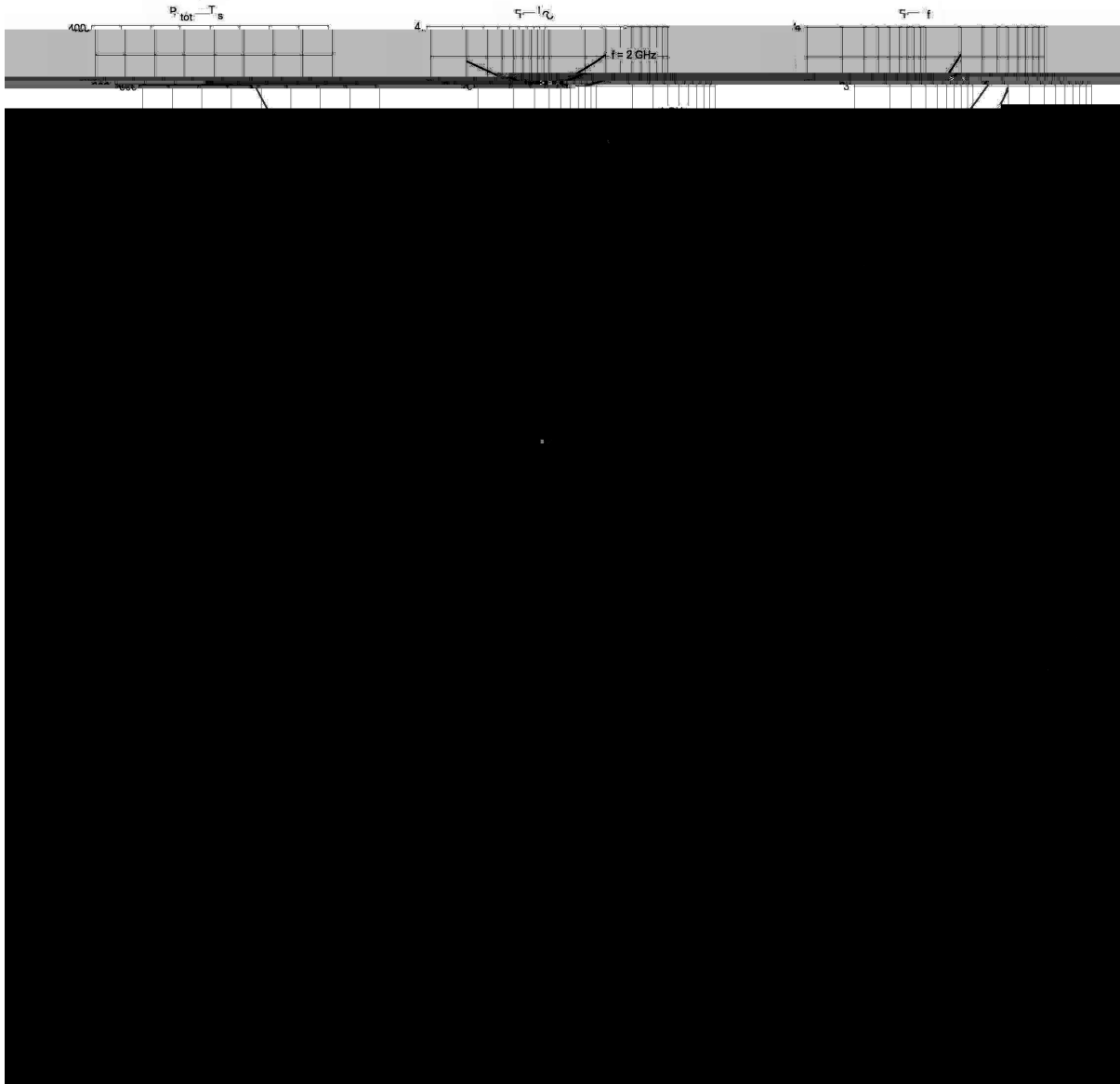
**/ Marking**

$h_{FE}$ Range	>40
Marking	HR2P

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	15	V
Collector to Emitter Voltage	$V_{CEO}$	12	V
Emitter to Base Voltage	$V_{EBO}$	2.0	V
Collector Current - Continuous	$I_C$	35	mA
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Min
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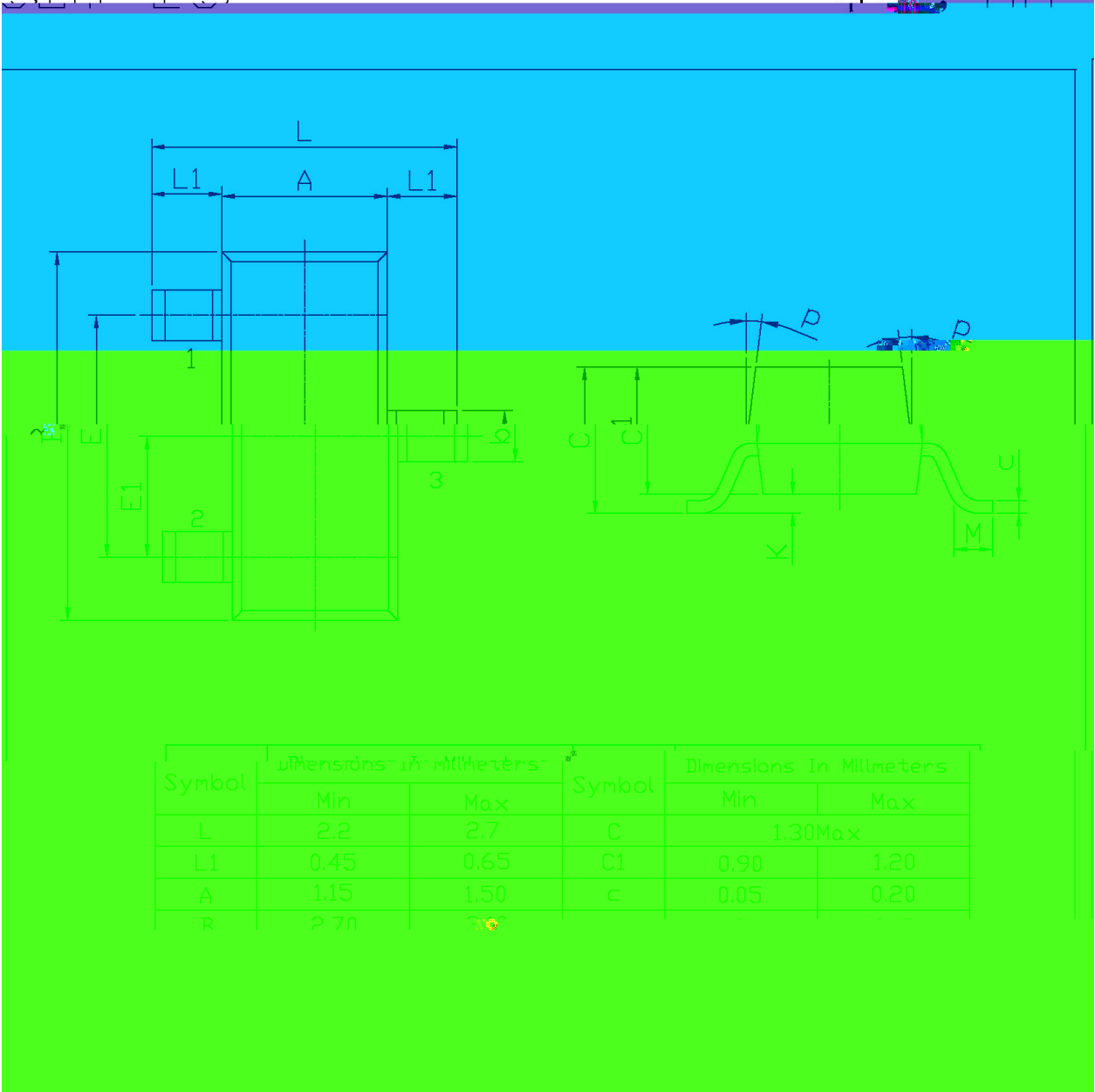
/ **Electrical Characteristic Curve**



/ Package Dimensions

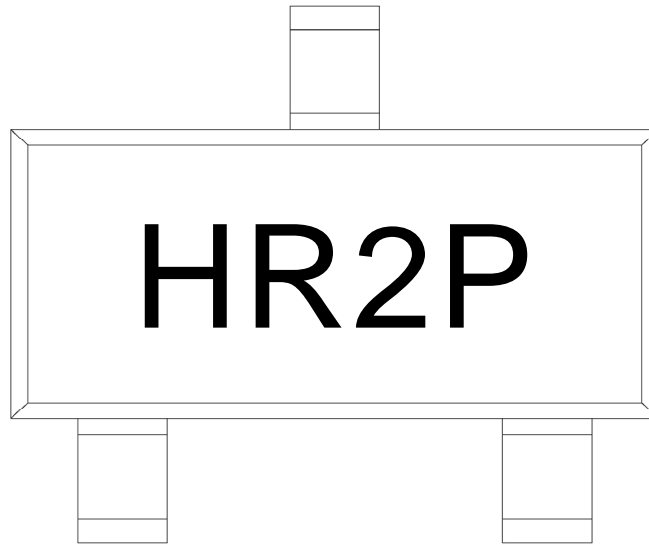
SOT-23

单位: mm



Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
R	2.70	3.00			

**/ Marking Instructions**



H

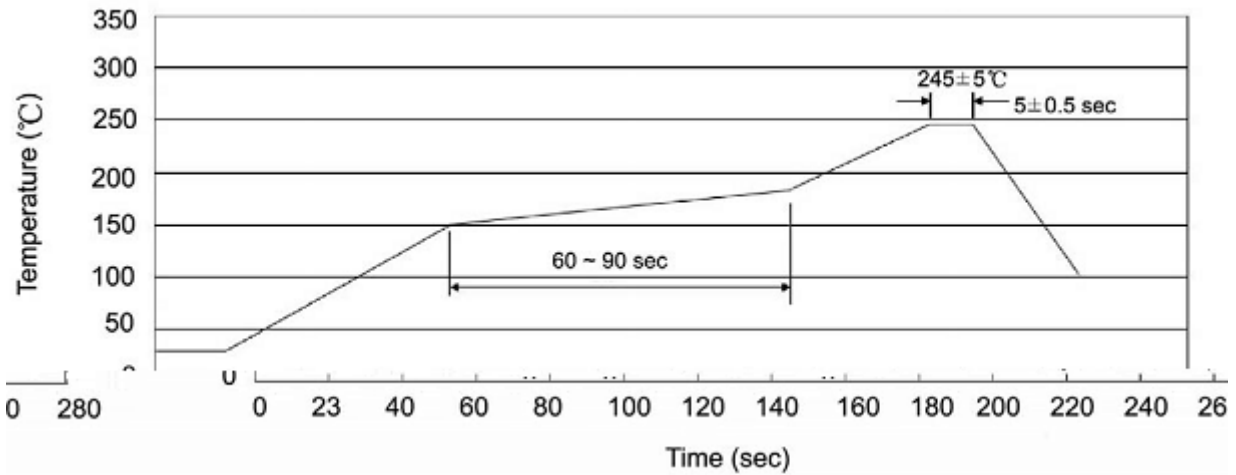
2RP

Note:

H: Company Code.

2RP: Product Type Code.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |           |        |   |
|---|-------|-----|-----------|--------|---|
| 1 | 25    | 150 | 60        | 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     | 5±0.5sec; |        | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10        | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱	盒	箱	

/ Notices